

# MC14516B

## Binary Up/Down Counter

The MC14516B synchronous up/down binary counter is constructed with MOS P-channel and N-channel enhancement mode devices in a monolithic structure.

This counter can be preset by applying the desired value, in binary, to the Preset inputs (P0, P1, P2, P3) and then bringing the Preset Enable (PE) high. The direction of counting is controlled by applying a high (for up counting) or a low (for down counting) to the UP/DOWN input. The state of the counter changes on the positive transition of the clock input.

Cascading can be accomplished by connecting the  $\overline{\text{Carry Out}}$  to the  $\overline{\text{Carry In}}$  of the next stage while clocking each counter in parallel. The outputs (Q0, Q1, Q2, Q3) can be reset to a low state by applying a high to the reset (R) pin.

This CMOS counter finds primary use in up/down and difference counting. Other applications include: (1) Frequency synthesizer applications where low power dissipation and/or high noise immunity is desired, (2) Analog-to-Digital and Digital-to-Analog conversions, and (3) Magnitude and sign generation.

### Features

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Speed
- Logic Edge-Clocked Design — Count Occurs on Positive Going Edge of Clock
- Single Pin Reset
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky Load Over the Rated Temperature Range
- These Devices are Pb-Free and are RoHS Compliant

### MAXIMUM RATINGS (Voltages Referenced to $V_{SS}$ )

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	$V_{DD}$	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	$V_{in}, V_{out}$	-0.5 to $V_{DD}$ + 0.5	V
Input or Output Current (DC or Transient) per Pin	$I_{in}, I_{out}$	$\pm 10$	mA
Power Dissipation, per Package (Note 1)	$P_D$	500	mW
Ambient Temperature Range	$T_A$	-55 to +125	°C
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Lead Temperature (8-Second Soldering)	$T_L$	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

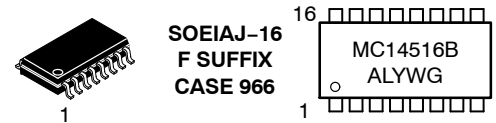
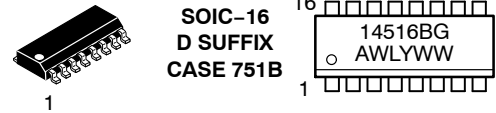
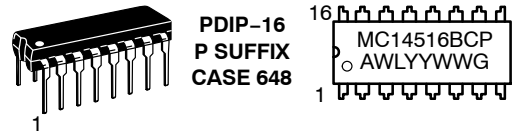
1. Temperature Derating: Plastic "P and D/DW"  
Packages: - 7.0 mW/°C From 65°C To 125°C



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### MARKING DIAGRAMS



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

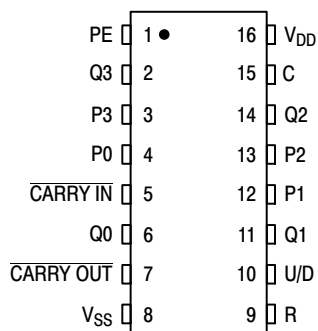
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

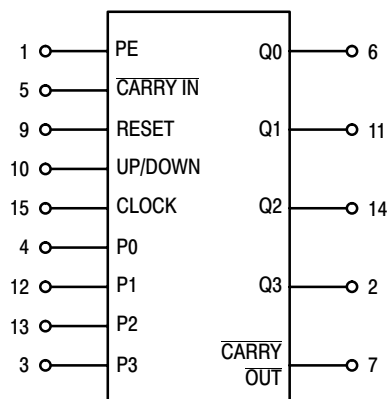
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

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## PIN ASSIGNMENT



## BLOCK DIAGRAM



V<sub>DD</sub> = PIN 16  
V<sub>SS</sub> = PIN 8

## TRUTH TABLE

Carry In	Up/Down	Preset Enable	Reset	Clock	Action
1	X	0	0	X	No Count
0	1	0	0	↗	Count Up
0	0	0	0	↘	Count Down
X	X	1	0	X	Preset
X	X	X	1	X	Reset

X = Don't Care

NOTE: When counting up, the  $\overline{\text{Carry Out}}$  signal is normally high and is low only when Q0 through Q3 are high and  $\overline{\text{Carry In}}$  is low. When counting down,  $\overline{\text{Carry Out}}$  is low only when Q0 through Q3 and  $\overline{\text{Carry In}}$  are low.

## ORDERING INFORMATION

Device	Package	Shipping†
MC14516BCPG	PDIP-16 (Pb-Free)	25 Units / Rail
MC14516BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14516BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14516BFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC14516BFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## ELECTRICAL CHARACTERISTICS (Voltages Referenced to $V_{SS}$ )

Characteristic	Symbol	$V_{DD}$ Vdc	- 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage $V_{in} = V_{DD}$ or 0  $V_{in} = 0$ or $V_{DD}$	"0" Level  $V_{OL}$	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
		10	-	0.05	-	0	0.05	-	0.05	
		15	-	0.05	-	0	0.05	-	0.05	
	"1" Level  $V_{OH}$	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
		10	9.95	-	9.95	10	-	9.95	-	
		15	14.95	-	14.95	15	-	14.95	-	
Input Voltage $(V_O = 4.5$ or $0.5$ Vdc) $(V_O = 9.0$ or $1.0$ Vdc) $(V_O = 13.5$ or $1.5$ Vdc)  $(V_O = 0.5$ or $4.5$ Vdc) $(V_O = 1.0$ or $9.0$ Vdc) $(V_O = 1.5$ or $13.5$ Vdc)	"0" Level  $V_{IL}$	5.0	-	1.5	-	2.25	1.5	-	1.5	Vdc
		10	-	3.0	-	4.50	3.0	-	3.0	
		15	-	4.0	-	6.75	4.0	-	4.0	
	"1" Level  $V_{IH}$	5.0	3.5	-	3.5	2.75	-	3.5	-	Vdc
		10	7.0	-	7.0	5.50	-	7.0	-	
		15	11	-	11	8.25	-	11	-	
Output Drive Current $(V_{OH} = 2.5$ Vdc) $(V_{OH} = 4.6$ Vdc) $(V_{OH} = 9.5$ Vdc) $(V_{OH} = 13.5$ Vdc)  $(V_{OL} = 0.4$ Vdc) $(V_{OL} = 0.5$ Vdc) $(V_{OL} = 1.5$ Vdc)	Source  $I_{OH}$	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc
		5.0	-0.64	-	-0.51	-0.88	-	-0.36	-	
		10	-1.6	-	-1.3	-2.25	-	-0.9	-	
		15	-4.2	-	-3.4	-8.8	-	-2.4	-	
	Sink  $I_{OL}$	5.0	0.64	-	0.51	0.88	-	0.36	-	mAdc
		10	1.6	-	1.3	2.25	-	0.9	-	
15		4.2	-	3.4	8.8	-	2.4	-		
Input Current	$I_{in}$	15	-	$\pm 0.1$	-	$\pm 0.00001$	$\pm 0.1$	-	$\pm 1.0$	$\mu$ Adc
Input Capacitance ( $V_{in} = 0$ )	$C_{in}$	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	$I_{DD}$	5.0	-	5.0	-	0.005	5.0	-	150	$\mu$ Adc
		10	-	10	-	0.010	10	-	300	
		15	-	20	-	0.015	20	-	600	
Total Supply Current (Note 3, 4) (Dynamic plus Quiescent, Per Package) $(C_L = 50$ pF on all outputs, all buffers switching)	$I_T$	5.0	$I_T = (0.58 \mu\text{A/kHz}) f + I_{DD}$							$\mu$ Adc
		10	$I_T = (1.20 \mu\text{A/kHz}) f + I_{DD}$							
		15	$I_T = (1.70 \mu\text{A/kHz}) f + I_{DD}$							

- Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
- The formulas given are for the typical characteristics only at 25°C.
- To calculate total supply current at loads other than 50 pF:  $I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) V f k$  where:  $I_T$  is in  $\mu\text{A}$  (per package),  $C_L$  in pF,  $V = (V_{DD} - V_{SS})$  in volts,  $f$  in kHz is input frequency, and  $k = 0.001$ .

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## SWITCHING CHARACTERISTICS (Note 5) ( $C_L = 50$ pF, $T_A = 25^\circ\text{C}$ )

Characteristic	Symbol	$V_{DD}$	All Types			Unit
			Min	Typ (Note 6)	Max	
Output Rise and Fall Time $t_{TLH}, t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}, t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}, t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	$t_{TLH},$ $t_{THL}$	5.0 10 15	– – –	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  Clock to $\overline{\text{Carry Out}}$ $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  $\overline{\text{Carry In}}$ to $\overline{\text{Carry Out}}$ $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  Preset or Reset to Q $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  Preset or Reset to $\overline{\text{Carry Out}}$ $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 465 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 192 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 125 \text{ ns}$	$t_{PLH},$ $t_{PHL}$	5.0 10 15	– – –	315 130 100	630 260 200	ns
	$t_{PLH},$ $t_{PHL}$	5.0 10 15	– – –	315 130 100	630 260 200	ns
	$t_{PLH},$ $t_{PHL}$	5.0 10 15	– – –	180 80 60	360 160 120	ns
	$t_{PLH},$ $t_{PHL}$	5.0 10 15	– – –	315 130 100	630 360 200	ns
	$t_{PLH},$ $t_{PHL}$	5.0 10 15	– – –	550 225 150	1100 450 300	ns
Reset Pulse Width	$t_w$	5.0 10 15	380 200 160	190 100 80	– – –	ns
Clock Pulse Width	$t_{WH}$	5.0 10 15	350 170 140	200 100 75	– – –	ns
Clock Pulse Frequency	$f_{cl}$	5.0 10 15	– – –	3.0 6.0 8.0	1.5 3.0 4.0	MHz
Preset or Reset Removal Time The Preset or Reset signal must be low prior to a positive-going transition of the clock.	$t_{rem}$	5.0 10 15	650 230 180	325 115 90	– – –	ns
Clock Rise and Fall Time	$t_{TLH},$ $t_{THL}$	5.0 10 15	– – –	– – –	15 5 4	$\mu\text{s}$
Setup Time Carry In to Clock	$t_{su}$	5.0 10 15	260 120 100	130 60 50	– – –	ns
Hold Time Clock to $\overline{\text{Carry In}}$	$t_h$	5.0 10 15	0 20 20	–60 –20 0	– – –	ns
Setup Time Up/Down to Clock	$t_{su}$	5.0 10 15	500 200 150	250 100 75	– – –	ns
Hold Time Clock to Up/Down	$t_h$	5.0 10 15	–70 –10 0	–160 –60 –40	– – –	ns
Setup Time Pn to PE	$t_{su}$	5.0 10 15	–40 –30 –25	–120 –70 –50	– – –	ns
Hold Time PE to Pn	$t_h$	5.0 10 15	480 420 420	240 210 210	– – –	ns
Preset Enable Pulse Width	$t_{WH}$	5.0 10 15	200 100 80	100 50 40	– – –	ns

5. The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

6. Data labelled "Typ" is not to be used for design purposes but is intended as an Indication of the IC's potential performance.

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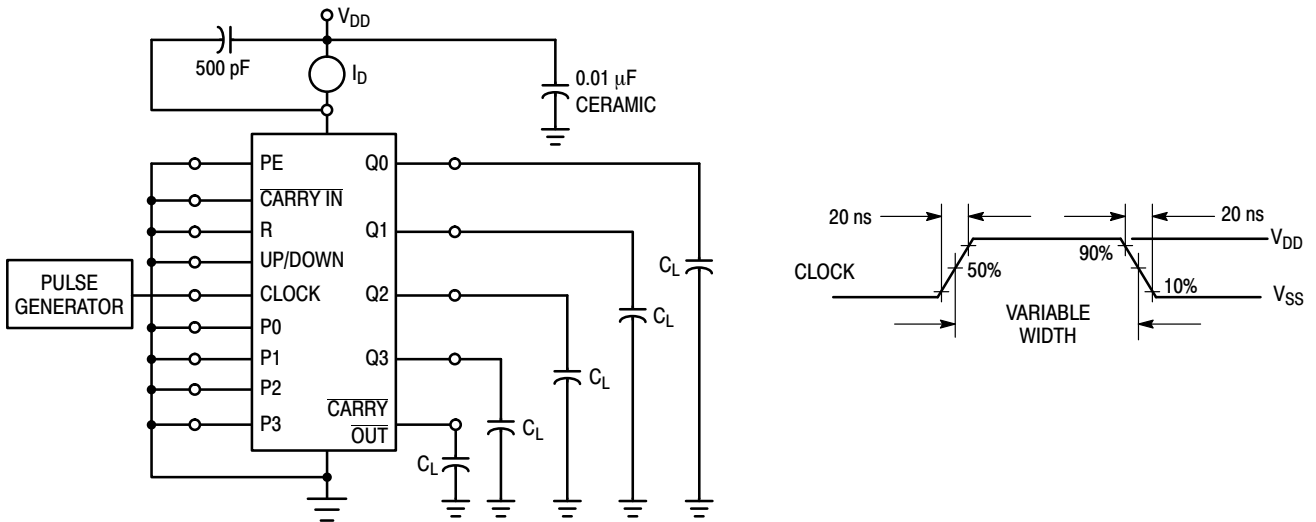
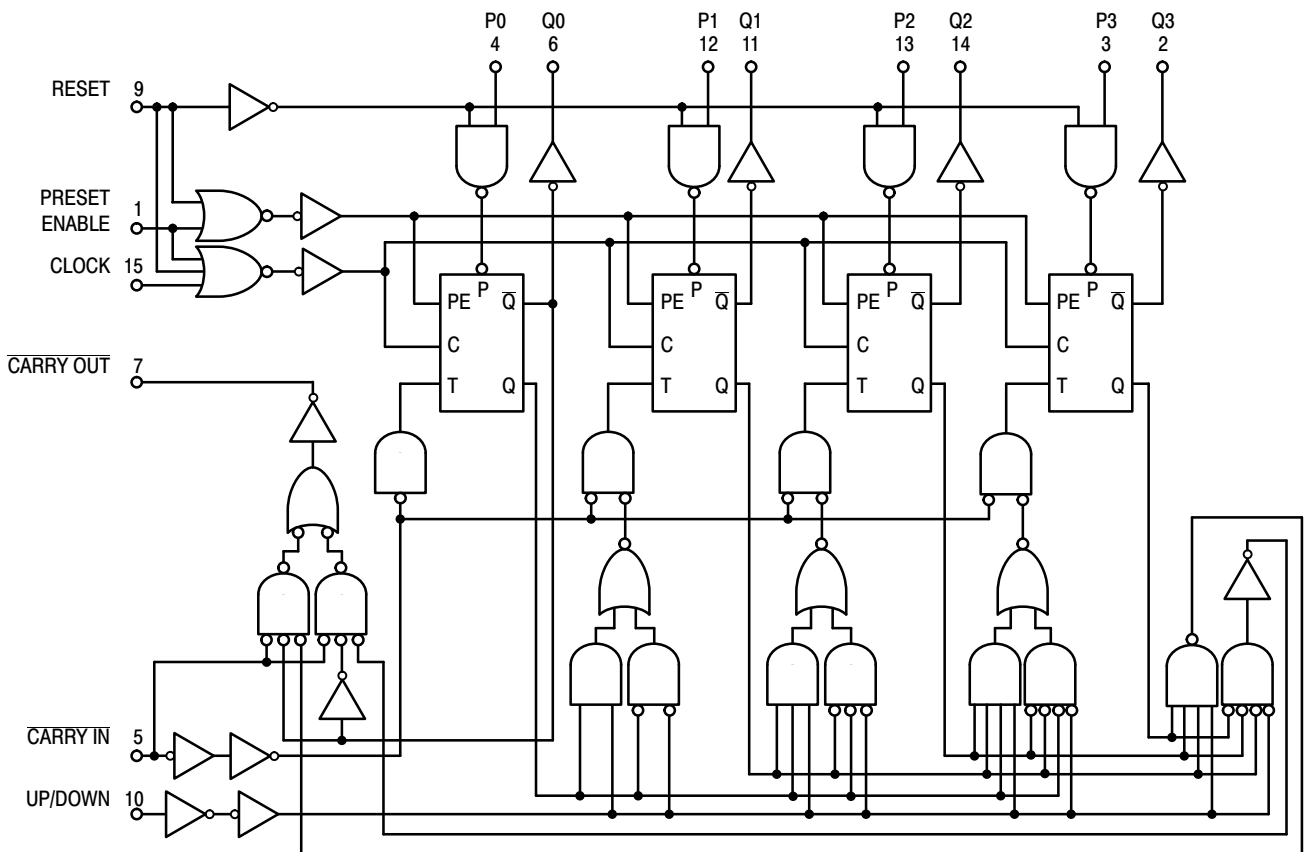


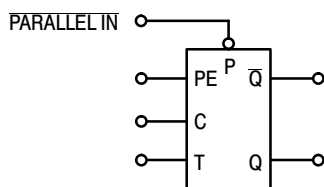
Figure 1. Power Dissipation Test Circuit and Waveform

## LOGIC DIAGRAM



# MC14516B

## TOGGLE FLIP-FLOP



## FLIP-FLOP FUNCTIONAL TRUTH TABLE

Preset Enable	Clock	T	$Q_{n+1}$
1	X	X	Parallel In
0		0	$Q_n$
0		1	$\overline{Q}_n$
0		X	$Q_n$

X = Don't Care

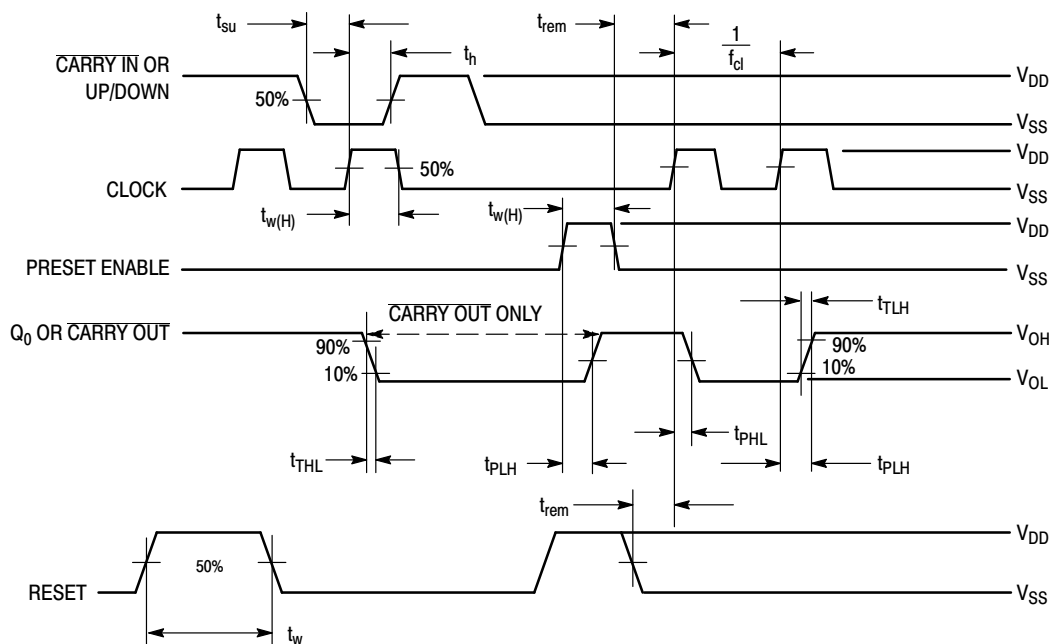


Figure 2. Switching Time Waveforms

## PIN DESCRIPTIONS

### INPUTS

**P0, P1, P2, P3, Preset Inputs (Pins 4, 12, 13, 3)** — Data on these inputs is loaded into the counter when PE is taken high.

**Carry In, (Pin 5)** — This active-low input is used when Cascading stages. Carry In is usually connected to Carry Out of the previous stage. While high, Clock is inhibited.

**Clock, (Pin 15)** — Binary data is incremented or decremented, depending on the direction of count, on the positive transition of this input.

### OUTPUTS

**Q0, Q1, Q2, Q3, Binary outputs (Pins 6, 11, 14, 2)** — Binary data is present on these outputs with Q0 corresponding to the least significant bit.

**Carry Out, (Pin 7)** — Used when cascading stages, Carry Out is usually connected to Carry In of the next stage. This synchronous output is active low and may also be used to indicate terminal count.

### CONTROLS

**PE, Preset Enable, (Pin 1)** — Asynchronously loads data on the Preset Inputs. This pin is active high and inhibits the clock when high.

**R, Reset, (Pin 9)** — Asynchronously resets the Q outputs to a low state. This pin is active high and inhibits the clock when high.

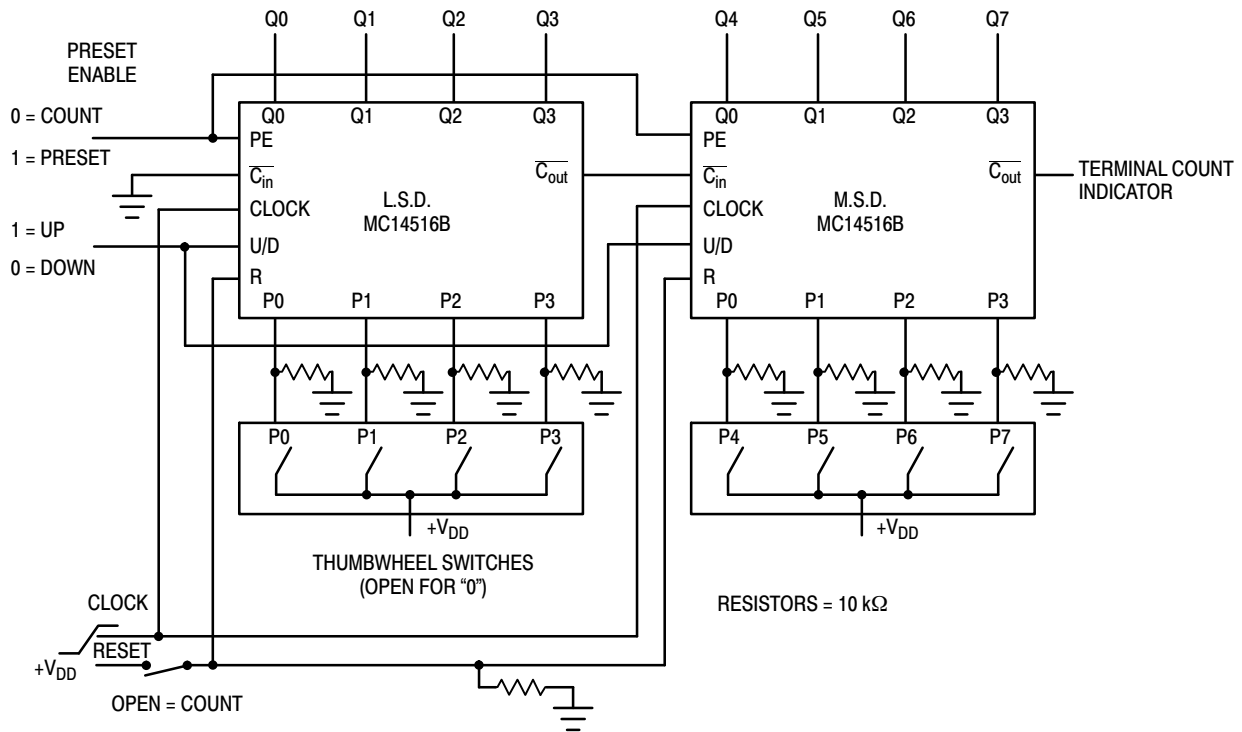
**Up/Down, (Pin 10)** — Controls the direction of count, high for up count, low for down count.

### SUPPLY PINS

**VSS, Negative Supply Voltage, (Pin 8)** — This pin is usually connected to ground.

**VDD, Positive Supply Voltage, (Pin 16)** — This pin is connected to a positive supply voltage ranging from 3.0 V to 18 V.

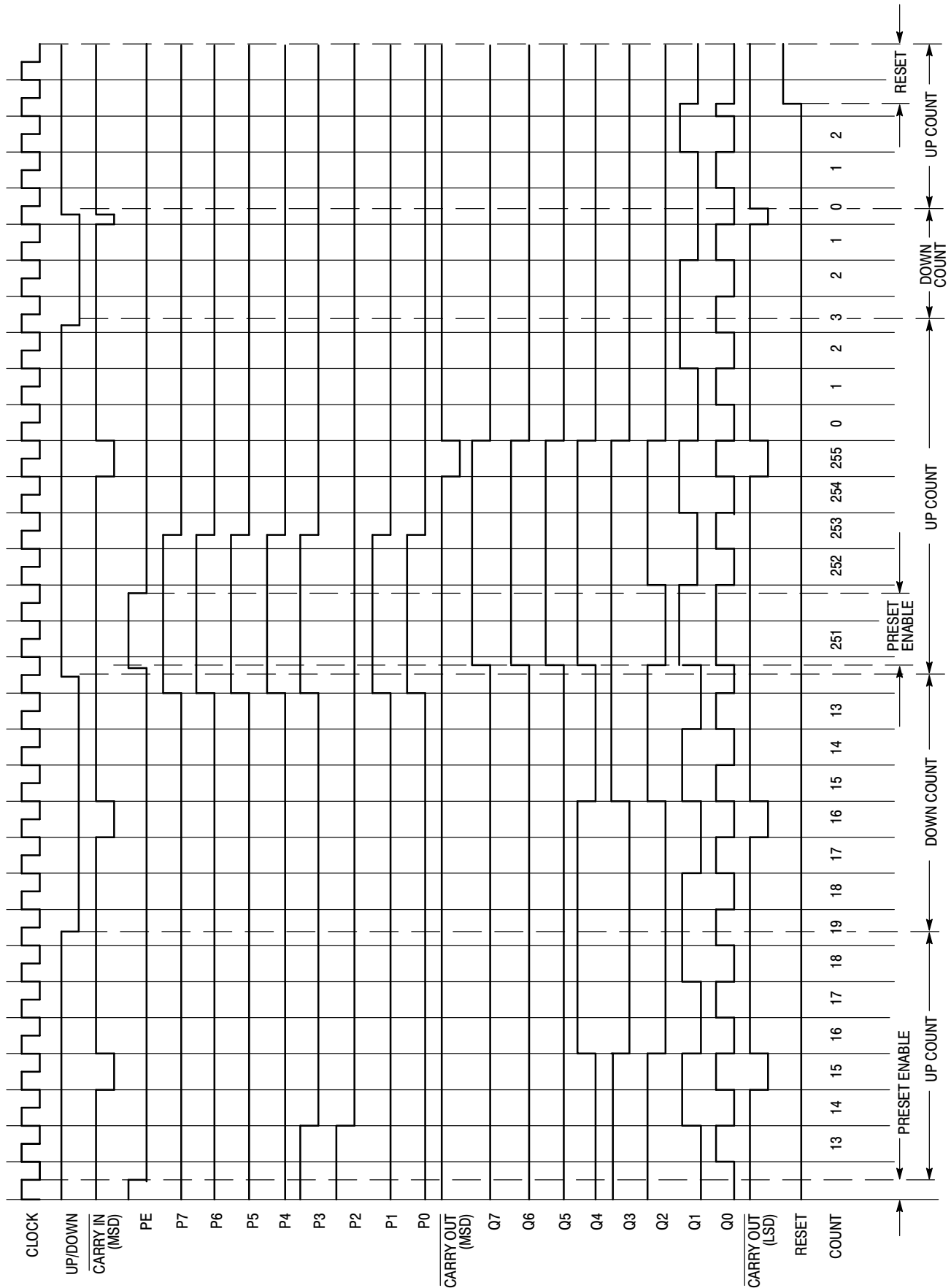
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NOTE: The Least Significant Digit (L.S.D.) counts from a preset value once Preset Enable (PE) goes low. The Most Significant Digit (M.S.D.) is disabled while  $\overline{C_{in}}$  is high. When the count of the L.S.D. reaches 0 (count down mode) or reaches 15 (count up mode),  $\overline{C_{out}}$  goes low for one complete clock cycle, thus allowing the next counter to decrement/increment one count. (See Timing Diagram) The L.S.D. now counts through another cycle (15 clock pulses) and the above cycle is repeated.

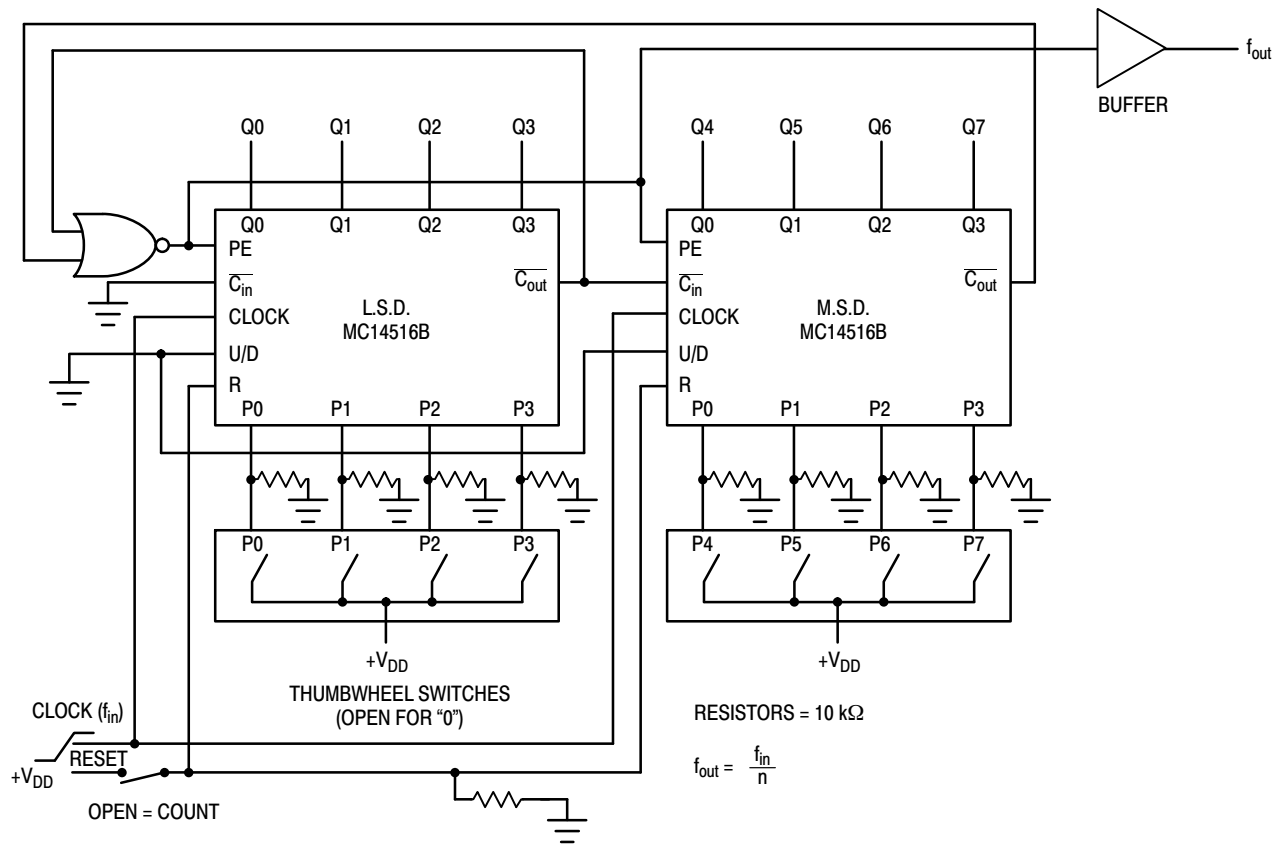
**Figure 3. Presetable Cascaded 8-Bit Up/Down Counter**

TIMING DIAGRAM FOR THE PRESETTABLE CASCADED 8-BIT UP/DOWN COUNTER





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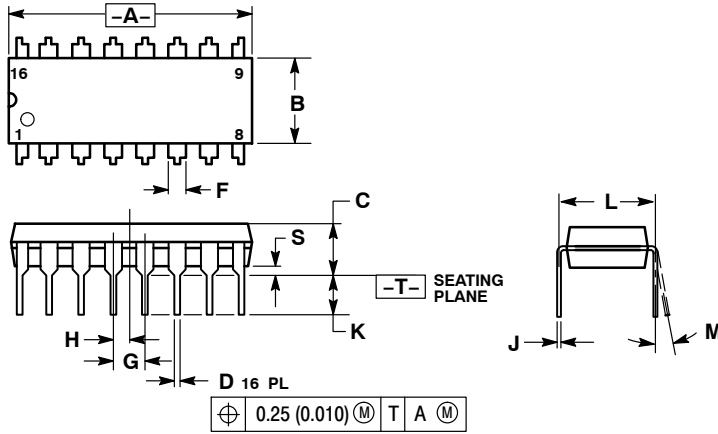
NOTE: The programmable frequency divider can be set by applying the desired divide ratio, in binary, to the preset inputs. For example, the maximum divide ratio of 255 may be obtained by applying a 1111 1111 to the preset inputs P0 to P7. For this divide operation, both counters should be configured in the count down mode. The divide ratio of zero is an undefined state and should be avoided.

**Figure 4. Programmable Cascaded Frequency Divider**

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## PACKAGE DIMENSIONS

PDIP-16  
CASE 648-08  
ISSUE T

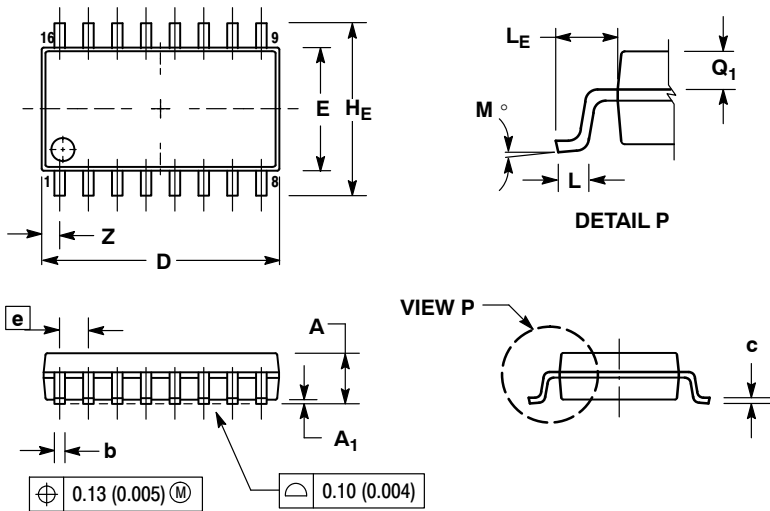


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SOEIAJ-16  
CASE 966-01  
ISSUE A



NOTES:

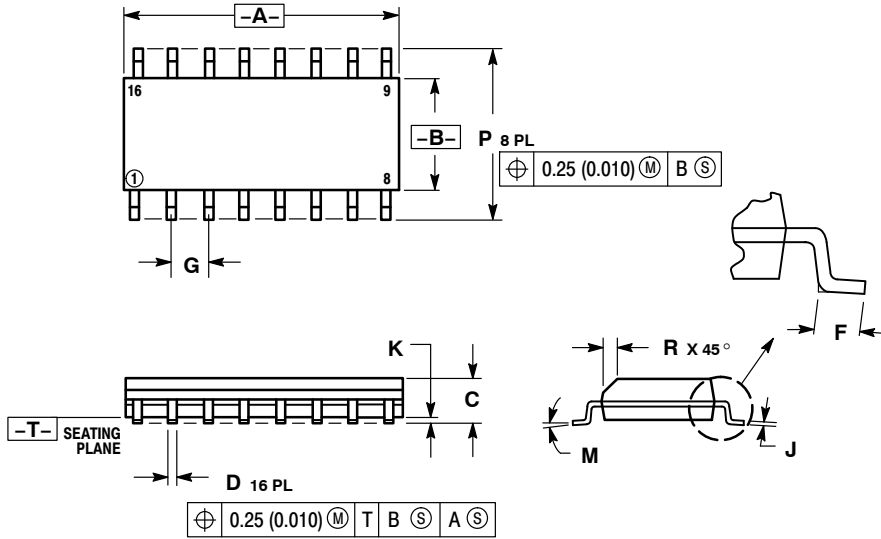
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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## PACKAGE DIMENSIONS

SOIC-16  
CASE 751B-05  
ISSUE K

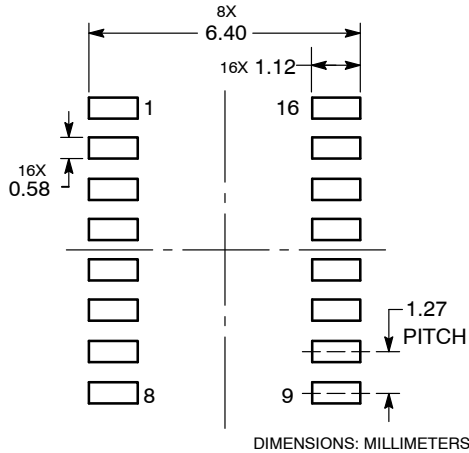


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0° 7°		0° 7°	
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

### SOLDERING FOOTPRINT



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